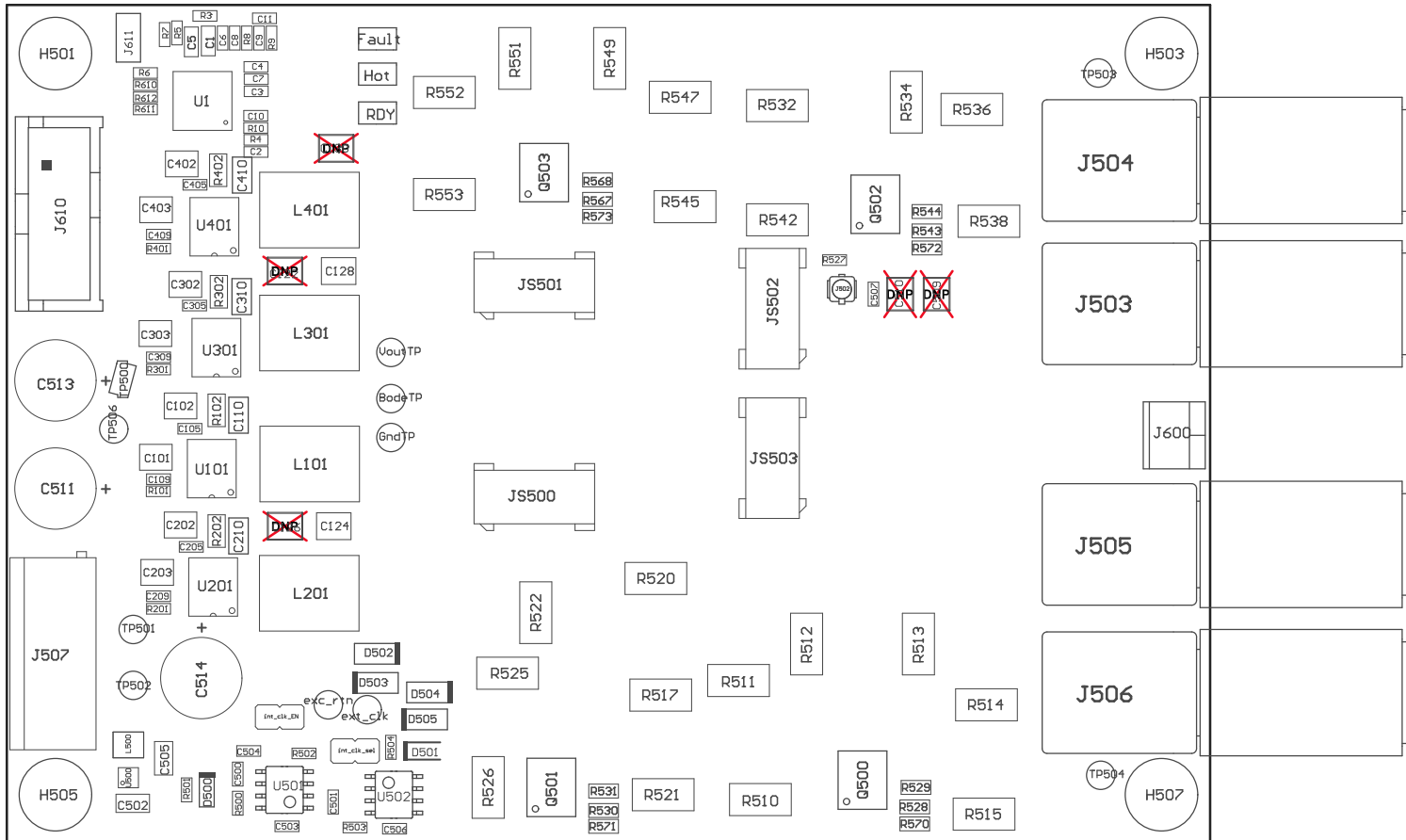
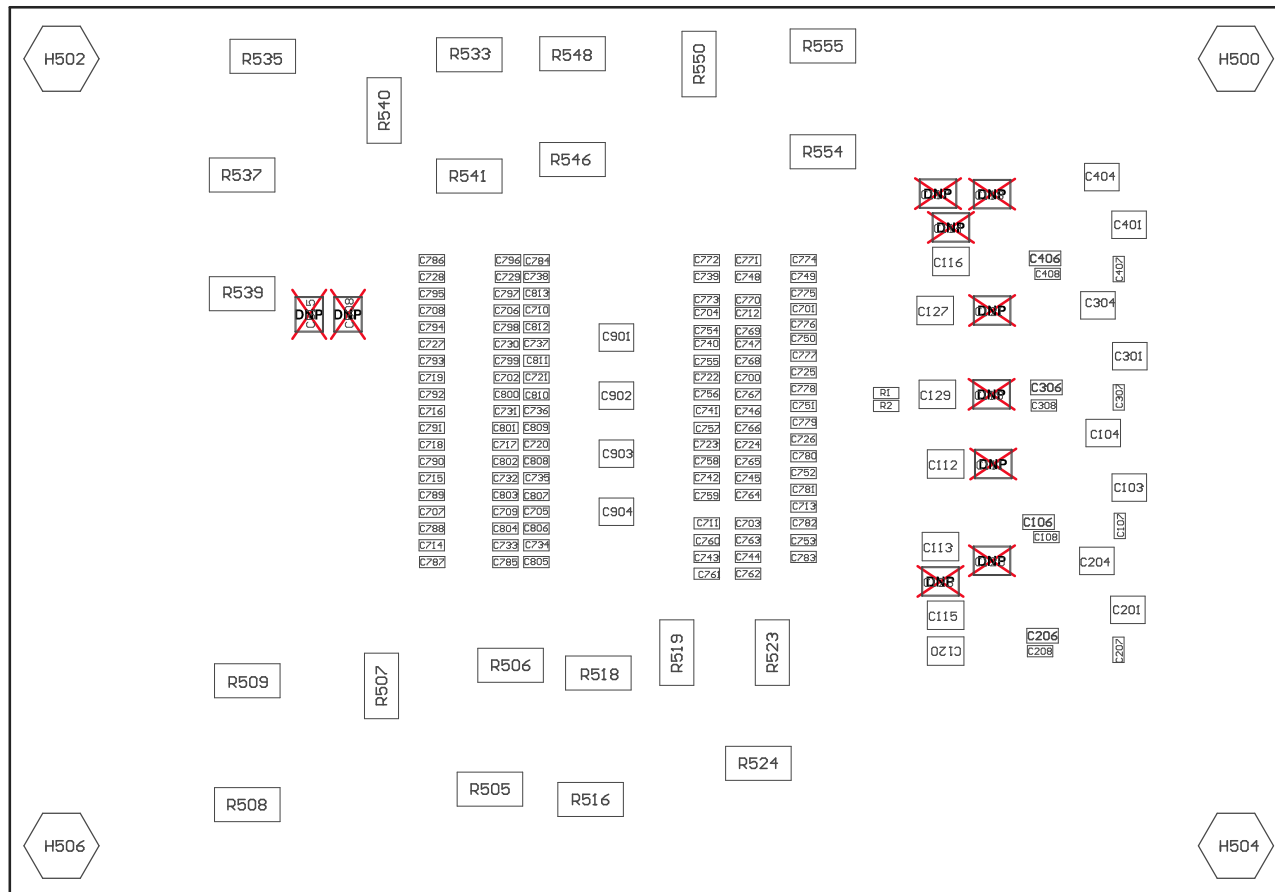


Z250 These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z250 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z250 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20176	REV: B	SUN REV: Not In VersionControl
	TID #: PMP20176		
PLOT NAME = Top Assembly Drawing	GENERATED : 6/20/2017	10:49:05 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20176	REV: B	SUN REV: Not In VersionControl
	TID #: PMP20176		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/20/2017	10:49:07 AM	TEXAS INSTRUMENTS

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